# LAMPS meeting

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### Design of BDC at SAMURA

RDC Parameters

Drift length

Anode, potential wird Cathode (gas window

Table

100

80

Efficiency [%]

500 600 700

14





**.......** 

800 900

High voltage [V]

- o .

1000 1100 1200 1300



- um<sup>r</sup> Al-Kapton × 9
- xx yy xx yy (8 planes
- <u> 8 cm × 8 cm</u>
- 128 ch/chambé
- i-C<sub>4</sub>11<sub>in</sub> at 100 (50) tor
- -80 (16) µm<sup>i</sup> Kapton
- $1/L_r = 0.9 \times 10^{-2}$

----- Etot(z=1)

• Etot(z=3) • Etot(z=5)

• Etot(z=6)

•••• Etot(z=7) ••• Etot(z=8) ••••• Em1(z=1) ••••• Em1(z=3) ••••• Em1(z=5) ••••• Em1(z=6) ••••• Em1(z=7) ••••• Em1(z=8)

### Resolution ~ 150 um Operation voltage > 700 V

g g

### Conceptual design of BDC

Beam pipe : φ 10 cm or φ 15 cm
Beam size : <u>Unknown !!!</u>
Beam intensity : <u>Unknown !!!</u>
Only we knew the beam size of the SAMURA !!!
→ Assumed similar wire configuration as SAMURA

### Modules



Specifications
Signal input 64CH
Analog processing_circuit_Amp-Shaper-Discriminator (ASD)
•A/D Converter AD9212 (10bit) Sampling frequency 31.25MHz
•FPGA XC7K325T (Xillinx)
•TDC function Build in FPGA / Resolution 1ns
•FPGA Configuration option BPI Flash memory / JTAG / Remote JTAG
•CLOCK 40MHz LVCMOS (1) 125MHz LVDS (1)
•Gb Ethernet UTP (1000BASE-TX) or Optical (1000BASE-X)
•GTX Transceiver SFP connector
•I/O NIM input (3) NIM output (3) ASD test input (1) HDMI-A (2)
•Switch User DIP (4) SiTCP Network (1) FPGA Configuration (1) JTAG Local/Remote (1)
•Power 5.5V (0.4A) 3.8V (0.6A) 2V (2.7A) 1.8V (1.8A)

## Design of BDC

- Drift length : 2.5 mm
- Configuration: xx'yy'xx'yy'
- Anode wire : 20 um
- Potential wire : 80 um
- # of CH of x/x' plane : 32 ch
- # of CH of y/y' plane : 16 ch
- Active area : 160 x 80 mm<sup>2</sup>
- # of ASD module : **3 ASD**

- Drift length : 2.0 mm
- Configuration: xx'yy'xx'yy'
- Anode wire : 20 um
- Potential wire : 80 um
- # of CH of x/x' plane : 32 ch
- # of CH of y/y' plane : 32 ch
- Active area : 128 x 128 mm<sup>2</sup>
- # of ASD module : **4 ASD**

- Drift length : 2.0 mm
- Configuration: xx'uu'vv'xx'
- Anode wire : 20 um
- Potential wire : 80 um
- # of CH of x/x' plane : 32 ch
- # of CH of u/u' plane : 48 ch
- # of CH of v/v' plane : 48 ch
- # of ASD module : **5 ASD**



Drift length : 2.5 mm Active area : 160 x 80 mm2

Drift length : 2. mm Active area : 128 x 128 mm2

## Active area with design 3

Wire spacing : 2 mm

U,V angle (deg)	Active area (Y)	Wire # (X-plane)	Wire # (V,U planes)	Active area (X)
15	36	44	144	120
	36	44	144	130
	36	44	144	140
20	36	44	144	120
	35	45	140	130
	35	45	140	140
30	34	46	136	120
	34	46	136	130
	33	47	132	140





Potted at 05.30.55 on 13/06/19 with Garfield version 7.44.

Plotted at 05.30.57 on 13/06/19 with Garfield version

### **Drift** line



The wire spacing and the active area are same distance → Circle shape of electric field Drift time : ~ 40 ns (1000V)

### Garfield sim





Contours of V



### Garfield sim

### 2.0mm wire-spacing 2.0mm plan-space

Contours of V







## Mylar







#### Low pinhole rate aluminized polyester film for Scintillators made by double side aluminized polyester film for radiation detector

This EJ-590/B10 is an extremely thin polyester film evapolated on both sides with aluminum metal. The film is specifically fabricated for use in alpha and beta particle radiation detectors as a light-tight radiation window. It's extreme thinness precludes the absence of pinholes, and a light-tight radiation window is usually constructed with two closely laid layers of the film thus achieving light tightness by virtue of the mis-alignment of the pinholes.

The film is supplied on rolls with a maximum width of 323mm (12 · 3/4 inch) and maximum length of 7,620mm (25 feet). It should be handled in a clean environment with care to avoid wrinkling and abrasion.

It may be cemented to support frames by using a variety of commercial adhesives including acrylics, silicones and epoxies. It may be cleaned by rinsing with methanol or isopropyl alcohol or by gentle wiping with clean cotton soaked in alcohol.

This EJ-590/B10 also can be used as the reflector sheet for scintillators.

Specifications				
Thickness	2.0μm ( 8.0 x10 <sup>-5</sup> inch )			
Density	0.29mg / cm <sup>2</sup>			
aluminized layer thickness	1,000 angstroms per side			

#### Transparency by alpha and beta particles

2 layers will stop approximately 1 MeV of energy from an alpha particle 2 layers will stop approximately 20 keV of energy from a beta particle

#### Standard form

320mm wide x 5,800mm long roll 320mm wide x 7,500mm long roll Available in custom roll width up to 750mm

#### G-tech, Corp. local representative in Japan 365-1, Sayamagahara, Iruma-shi, Saitama 358-0032 Phone# 04-2935-2777 Fax# 04-2935-2778

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ELJEN top ELJEN products G-tech index

- EJ-590/B10 is discontinued
- G-tech (JAP)
- Type : B(11)
- thickness : 2.540 micron
- film base :Polyester



• 12 um Aluminized Mylar @ KRISS

### Wire

#### SAMURA

20 um Au-coated W/Re 

80 um Au-Al 





### Gold Plated Tungsten-Rhenium Wire



### Gold coated Tungsten Wire

Diameter	Microns	17.8	25.4	31.7	38.1	50.8	76.2
	Mils	0.7	1.0	1.25	1.5	2.0	3.0
ALW-29S (hard)							
Elongation (%)		1 - 4	1 - 4	1 - 4	1 - 4	1 - 4	1 - 4
Breaking Load (g)		7.5 - 8.0	17.0 - 19.0	24.0 - 27.0	35.0 - 38.0	55.0 - 65.0	120.0 - 140.0
ALW-29S (medium)							
Elongation (%)		1 - 4	1 – 4	1 - 4	1 - 4	1 - 4	1 - 4
Breaking Load (g)		7.0 - 7.5	15.0 - 17.0	21.0 - 24.0	30.0 - 34.0	45.0 - 55.0	110.0 - 120.0
ALW-29S (soft)							
Elongation (%)		1 - 4	1 - 4	1 - 4	1 - 4	1 - 4	1 - 4
Breaking Load (g)		6.0 - 7.0	13.0 - 15.0	19.0 - 21.0	25.0 - 30.0	39.0 - 45.0	100.0 - 110.0
Fusing Current (Amp)		0.3	0.5	0.7	1.0	1.4	1.8

### Soldering bench@KRISS





< Cathode & Sensor (50  $\mu$ m)>



< Cathode & Sensor (50  $\mu$ m) & Guard (20  $\mu$ m)>



## Schedule of wiring and requirements

### Schedule

- Design of PCB board : 1 week
- Fabrication of PCB boad : 1 week
- Wiring : 1 plane / 0.5 day \* 8 planes → abou 1 week
- Cathode plane : 1 week

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### Requirements

- Beam size !!!
- Beam size !!!
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